



# EMB2S THRU EMB8S

## GLASS PASSIVATED SUPER FAST RECOVERY BRIDGE RECTIFIERS

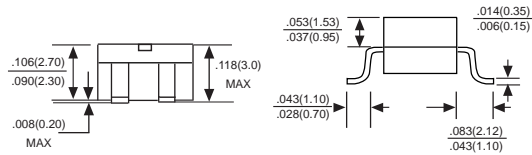
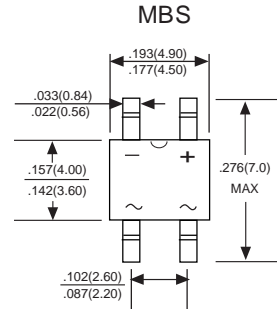
Voltage Range - 200 to 600Volts Current - 0.8/1.0 Ampere

### FEATURES

Ideal for printed circuit board  
 Reliable low cost construction utilizing  
 molded plastic technique  
 High temperature soldering guaranteed:  
 260°C/10 seconds at 5 lbs., (2.3kg) tension  
 Small size, simple installation  
 Leads solderable per MIL-STD-202, Method 208  
 High surge current capability  
 Super fast switching for high efficiency  
 Glass passivated chip junction  
 Green compound(halogen&Sb<sub>2</sub>O<sub>3</sub> free)

### MECHANICAL DATA

**Case:** Molded plastic body  
**Terminals:** Plated leads solderable per MIL-STD-750,  
 Method 2026  
**Polarity:** Polarity symbols marked on case  
**Mounting Position:** Any



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

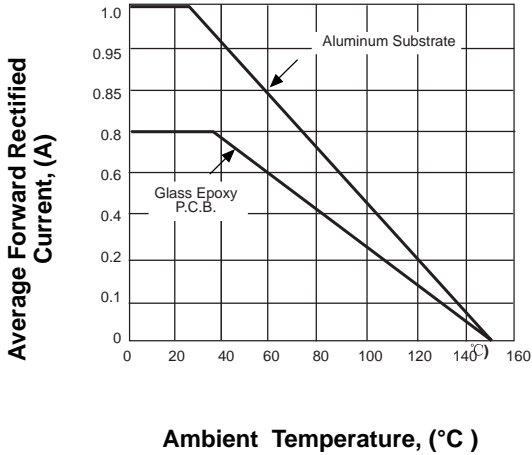
	SYMBOLS	EMB2S	EMB4S	EMB6S	EMB8S	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	200	400	600	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	V
Maximum DC blocking voltage	$V_{DC}$	100	200	400	600	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$		0.8 1.0			A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$		30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	$V_F$	0.95		1.25	1.7	V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ C$ $T_A=125^\circ C$	$I_R$		5.0 500			$\mu A$ $\mu A$
Typical thermal resistance(NOTE 3)	$R_{\theta JL}$ $R_{\theta JA}$		28 85			$^\circ C/W$
Maximum reverse recovery time (NOTE 4)	$t_{rr}$		35			ns
Operating temperature range	$T_J$		-55 to +150			$^\circ C$
storage temperature range	$T_{STG}$		-55 to +150			$^\circ C$

NOTES:1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.  
 2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.  
 3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.  
 4. Reverse recovery condition  $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$ .

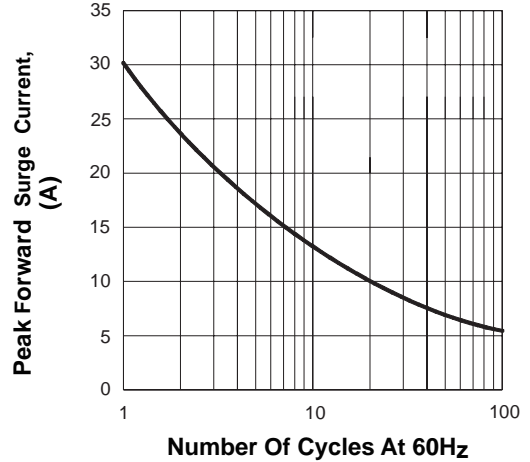


# RATINGS AND CHARACTERISTIC CURVES EMB2S THRU EMB8S

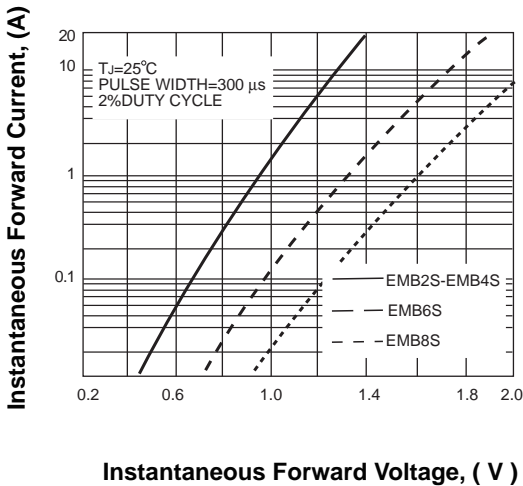
**FIG.1 FORWARD DERATING CURVE**



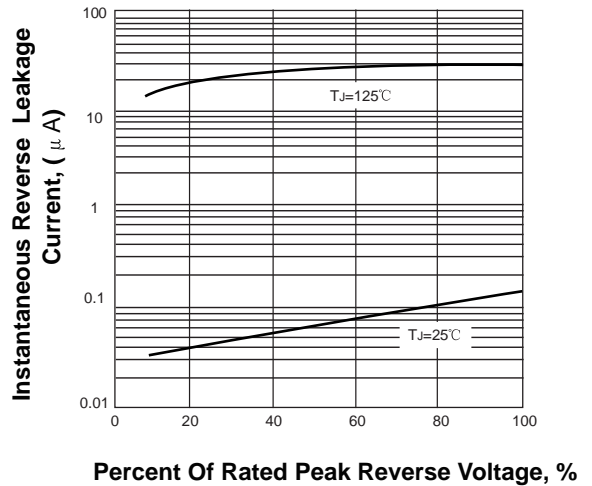
**FIG.2 PEAK FORWARD SURGE CURRENT**



**FIG.3 TYPICAL FORWARD CHARACTERISTICS**



**FIG.4 TYPICAL REVERSE CHARACTERISTICS**



单击下面可查看定价，库存，交付和生命周期等信息

[>>ZG\(中鑫半导体\)](#)